

10        a single track resistor (RB) co-integrated into a semiconductor body, wherein said single  
11      track resistor precedes every control connection (B) of said laterally designed bipolar transistors  
12      (T1-T3).

2.(Previously Amended)      The electrostatic discharge protective structure of claim 1, wherein  
said semiconductor body has embedded therein at least one emitter zone and at least one  
collector zone of the first conduction type and at least one base zone of the second, opposite  
conduction type, wherein a well-shaped region is inserted into said semiconductor body between  
said zones of the first conduction type and said base zone or said base zones, so as to extend the  
effective mean free path of the charge carriers to said base zone.

1    3.(Original)    The electrostatic discharge protective structure of claim 2, wherein said well-  
2    shaped region is connected to one of said zones of the first conduction type.

1    4.(Original)    The electrostatic discharge protective structure of claim 3, wherein said well-  
2    shaped region has the same conduction type as said zone to which it is connected, but has a lower  
3    dopant concentration.

5.(Original) The electrostatic discharge protective structure of claim 4, wherein said well-shaped region extends deeper into said semiconductor body than said zone which it adjoins or to which it is connected.

6.(Previously Amended) The electrostatic discharge protective structure of claim 5, wherein said base zones laterally enclose said emitter zones and said collector zones.

1 7.(Original) The electrostatic discharge protective structure of claim 6, wherein said  
2 semiconductor body has charge carriers of the first conduction type and that at least one further  
3 well of the second conduction type is embedded in said semiconductor body, and that said  
4 emitter zones, collector zones, and base zones and said well-shaped regions are embedded in said  
5 well.

1 8.(Original) The electrostatic discharge protective structure of claim 7, wherein said emitter  
2 zones and collector zones are designed as strips and are disposed alternately next to one  
3 another and parallel to one another.

1 9.(Original) The electrostatic discharge protective structure of claim 8, wherein said  
2 electrostatic discharge protective structure is configured and arranged in an essentially square  
3 layout.

1 10.(Original) The electrostatic discharge protective structure of claim 9, wherein in said emitter  
2 zones are through-contacted by said emitter electrodes, and said collector zones are through-  
3 contacted by said collector electrodes.

1 11.(Original) The electrostatic discharge protective structure of claim 8, wherein said emitter  
2 electrodes and said collector electrodes are connected via conductor tracks to oppositely situated  
3 voltage buses and form finger-like connections which are staggered with one another.

1 12.(Original) The electrostatic discharge protective structure of claim 8, wherein said bipolar  
2 transistors (T1-T3) are designed as field oxide transistors.